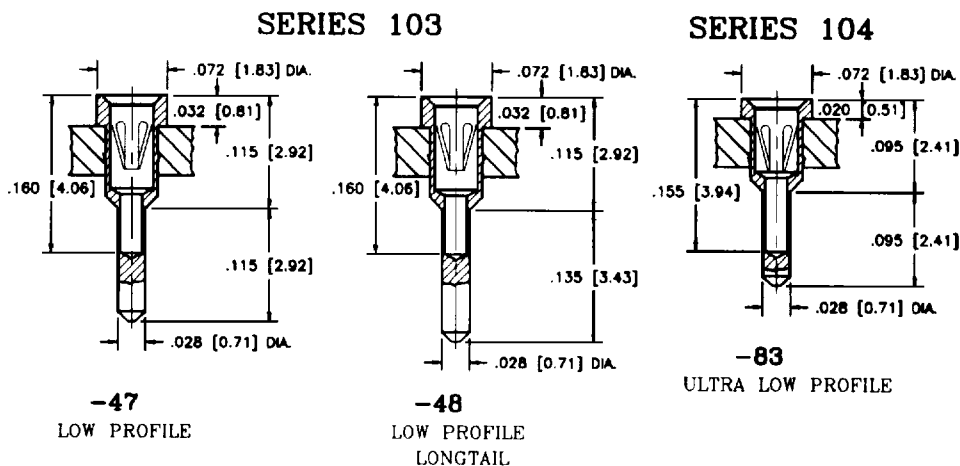


SERIES 103 LOW PROFILE DIP SOCKET (OPEN FRAME)

SERIES 104 ULTRA LOW PROFILE DIP SOCKET (OPEN FRAME)

SERIES 105 ULTRA LOW PROFILE DIP SOCKET (OPEN FRAME WITHOUT CROSSBARS)

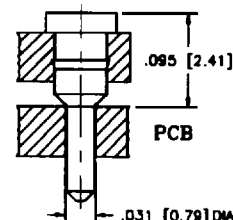
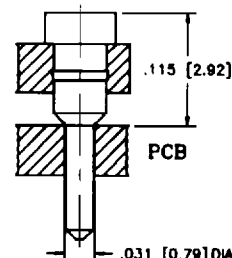
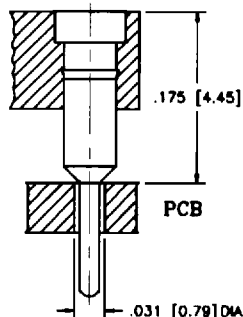
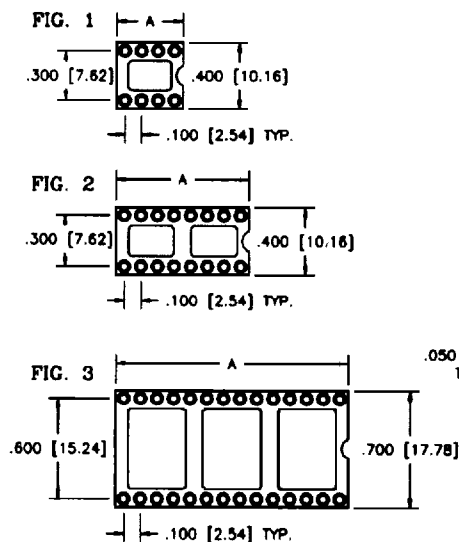
WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	306
	8	.400 [10.16]	308
	14	.700 [17.78]	314
FIG. 2	16	.800 [20.32]	316
	18	.900 [22.86]	318
	20	1.000 [25.40]	320
	22	1.100 [27.94]	322
	24	1.200 [30.48]	324
	28	1.400 [35.56]	328
FIG. 3	24	1.200 [30.48]	624
	28	1.400 [35.56]	628
	30	1.500 [38.10]	630
	32	1.600 [40.64]	632
	36	1.800 [45.72]	636
	40	2.000 [50.80]	640



STANDARD HEIGHT
ABOVE PCB
WITH -01 TERMINAL

34%
REDUCED HEIGHT
WITH -47 TERMINAL

46%
REDUCED HEIGHT
WITH -83 TERMINAL



CONTACT TYPE

S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR	GLASS FILLED POLYESTER
	UL 94V-0 LISTED
TERMINAL CONTACT	BRASS PER ASTM-B16
	BeCu PER ASTM-B194
OPERATING TEMP.	-65°C TO +125°C
CONTACT FORCES	
INSERTION	STANDARD 9 oz. AVG.
WITHDRAWAL	STANDARD 2 oz. MIN.

ORDERING INFORMATION

10X-XXX-XXX-PXX-B12			
SERIES	LOGO	INSULATOR MATERIAL	
103: LOW PROFILE		OTHER MATERIALS AVAILABLE	
104: ULTRA LOW PROFILE		CONSULT FACTORY	
105: WITHOUT CROSSBARS		PLATING: TERMINAL / CONTACT	
DIP - SPACING		P30: GOLD / GOLD	
NO. OF PINS		P31: TIN-LEAD / GOLD	
TERMINAL STYLE		P32: TIN-LEAD / TIN	
FOR OPTIONAL TERMINAL STYLES		OTHER PLATINGS AVAILABLE	
SEE TERMINAL STYLES		SEE OPTIONAL PLATINGS	
CONTACT TYPE			